

# 1ch Small Package High Side Switch ICs for USB Devices and Memory Cards

**BD2224G-LB BD2225G-LB**

## General Description

This is the product guarantees long time support in Industrial market.

BD2224G and BD2225G are low on-resistance N-channel MOSFET high-side power switches, optimized for Universal Serial Bus (USB) applications. BD2224G and BD2225G are equipped with the function of over-current detection, thermal shutdown, under-voltage lockout and soft-start.

## Key Specifications

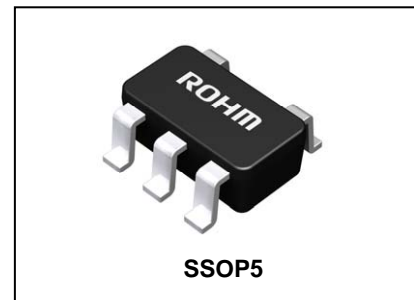
■ Input voltage range:	2.7V to 5.5V
■ ON resistance :	150mΩ(Typ.)
■ Over current threshold:	0.55A min., 1.0A max.
■ Standby current:	0.01μA (Typ.)
■ Operating temperature range:	-40°C to +85°C

**Package**  
SSOP5

W(Typ.) D(Typ.) H (Max.)  
2.90mm x 2.80mm x 1.25mm

## Features

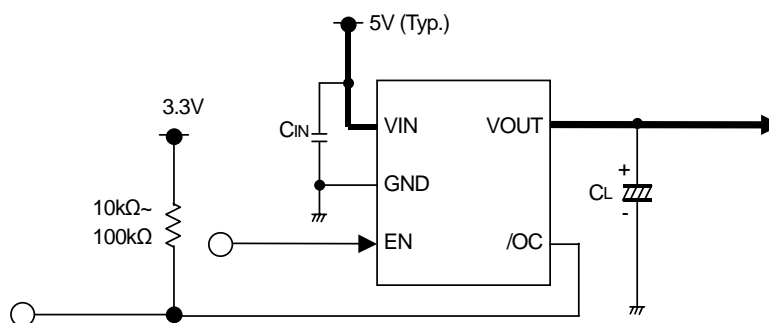
- Long time support a product for Industrial applications.
- Over-Current Detection
- Thermal Shutdown
- Open-Drain Fault Flag Output
- Under-Voltage Lockout
- Soft-Start Circuit
- Control Input Logic
  - Active-High (BD2224G)
  - Active-Low (BD2225G)



## Applications

Industrial Equipment,  
PC peripheral equipment, and so forth  
USB hub in consumer appliances, Car accessory, PC,

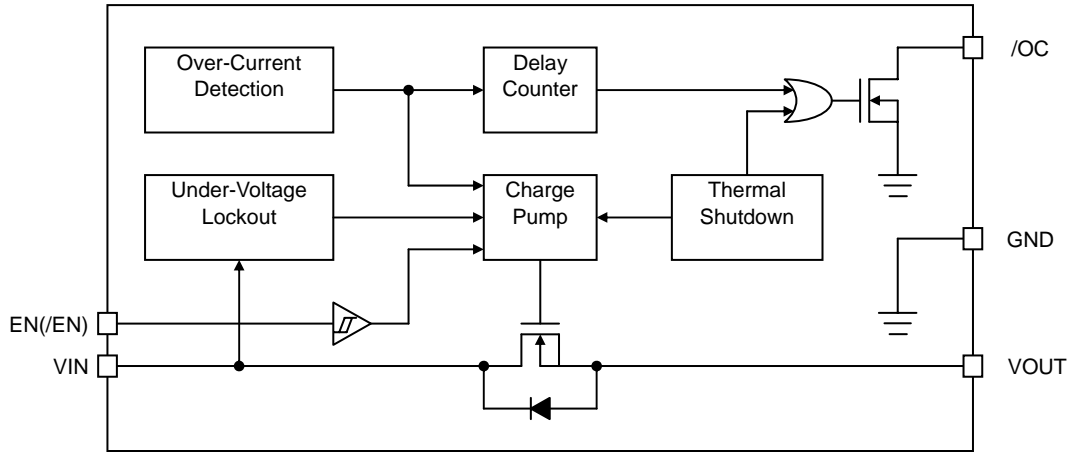
## Typical Application Circuit



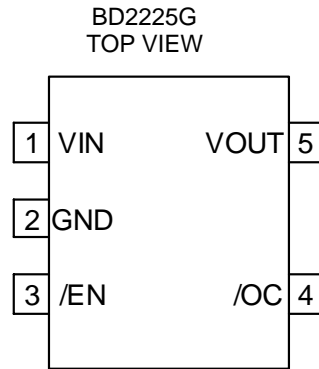
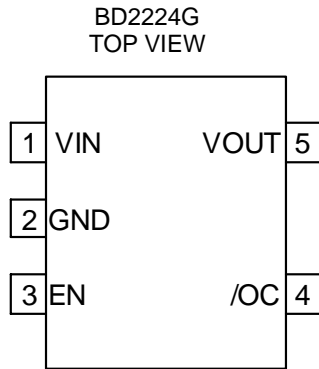
## Lineup

Over current threshold			Control input logic	Package		Orderable Part Number
Min.	Typ.	Max.				
550mA	780mA	1000mA	High	SSOP5	Reel of 3000	BD2224G – LBTR
550mA	780mA	1000ma	Low	SSOP5	Reel of 3000	BD2225G – LBTR

Block Diagram



Pin Configurations



Pin Description

Pin No.	Symbol	I/O	Function
1	VIN	-	Input switch and the supply voltage for the IC.
2	GND	-	Ground.
3	EN, /EN	I	Enable input. EN: High level input turns on the switch. (BD2224G) /EN: Low level input turns on the switch. (BD2225G)
4	/OC	O	Over-current notification terminal. Low level output during over-current or over-temperature condition. Open-drain fault flag output.
5	VOUT	O	Output switch.

**Absolute Maximum Ratings** (Ta=25°C)

Parameter	Symbol	Ratings	Unit
VIN Supply voltage	VIN	-0.3 to 6.0	V
EN(/EN) input voltage	VEN(/EN)	-0.3 to 6.0	V
/OC Voltage	V/OC	-0.3 to 6.0	V
/OC Sink current	I/OC	5	mA
VOUT Voltage	VOUT	-0.3 to VIN + 0.3	V
Storage temperature	TSTG	-55 to 150	°C
Power dissipation	Pd	675 <sup>*1</sup>	mW

\*1 Mounted on 70mm x 70mm x 1.6mm glass epoxy board. Reduce 5.4mW per 1°C above 25°C.

**Recommended Operating Range**

Parameter	Symbol	Ratings			Unit
		Min.	Typ.	Max.	
VIN operating voltage	VIN	2.7	5.0	5.5	V
Operating temperature	TOPR	-40	-	85	°C

**Electrical Characteristics** (VIN= 5V, Ta= 25°C, unless otherwise specified.)DC Characteristics

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Operating current	IDD	-	110	160	μA	VEN= 5V (BD2224G) V/EN= 0V (BD2225G) VOUT= open
Standby current	ISTB	-	0.01	5	μA	VEN= 0V (BD2224G) V/EN= 5V (BD2225G) VOUT= open
EN(/EN) input voltage	VEN(/EN)	2.0	-	-	V	High input
	VEN(/EN)	-	-	0.8	V	Low input
EN(/EN) input leakage	IEN(/EN)	-1	0.01	1	μA	VEN(/EN)= 0V or 5V
On-resistance	RON	-	150	200	mΩ	IOUT= 50mA
Over-current threshold	ITH	550	780	1000	mA	
Short circuit output current	ISC	350	-	-	mA	VOUT= 0V, RMS
/OC output low voltage	V/OC	-	-	0.4	V	I/OC= 0.5mA
UVLO threshold	VTUV	2.1	2.3	2.5	V	VIN increasing
		2.0	2.2	2.4	V	VIN decreasing

AC Characteristics

Parameter	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
Output rise time	TON1	-	1	6	ms	RL= 20Ω
Output turn-on time	TON2	-	1.5	10	ms	RL= 20Ω
Output fall time	TOFF1	-	1	20	μs	RL= 20Ω
Output turn-off time	TOFF2	-	3	40	μs	RL= 20Ω
/OC delay time	T/OC	10	15	20	ms	

Measurement Circuit

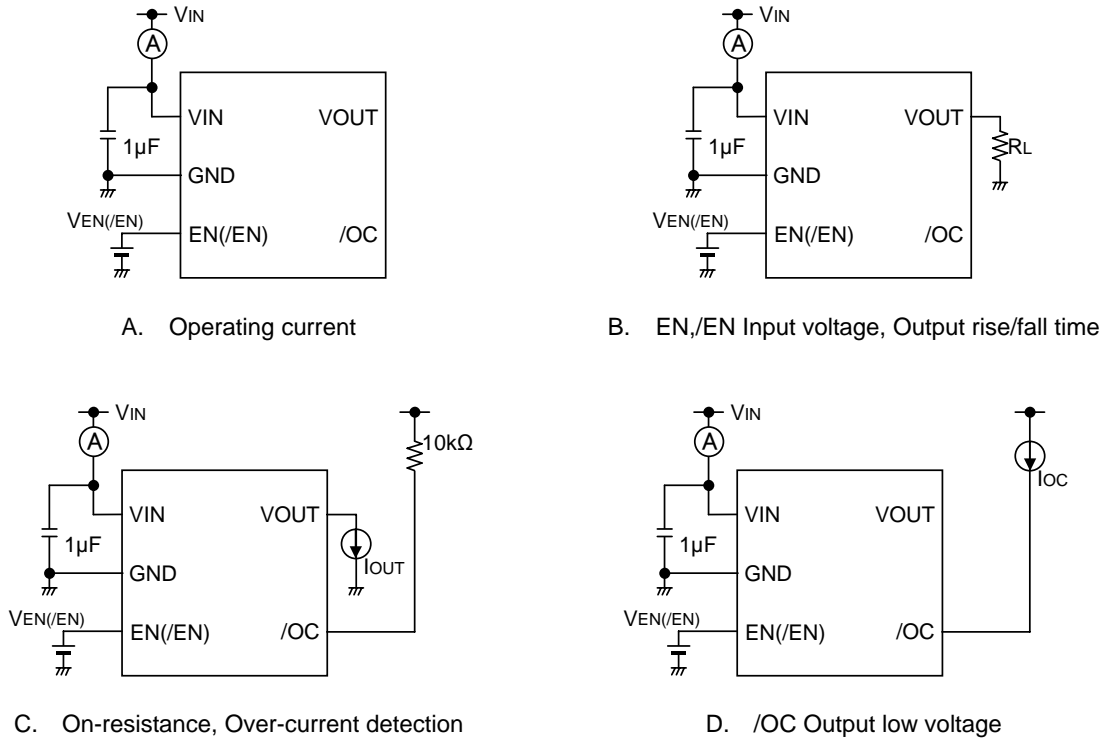


Figure 1. Measurement circuit

Timing Diagram

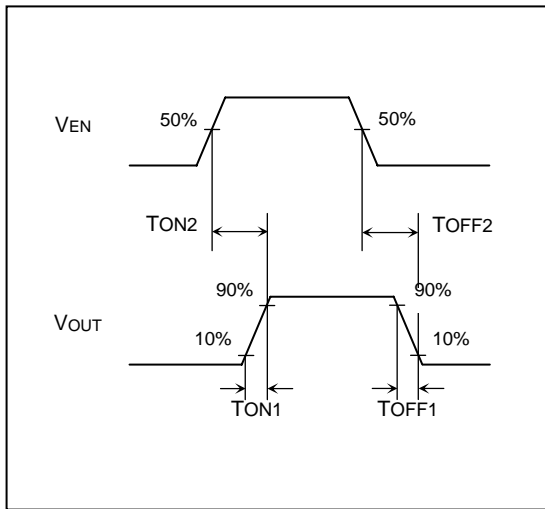


Figure 2. Output rise/fall time (BD2224G)

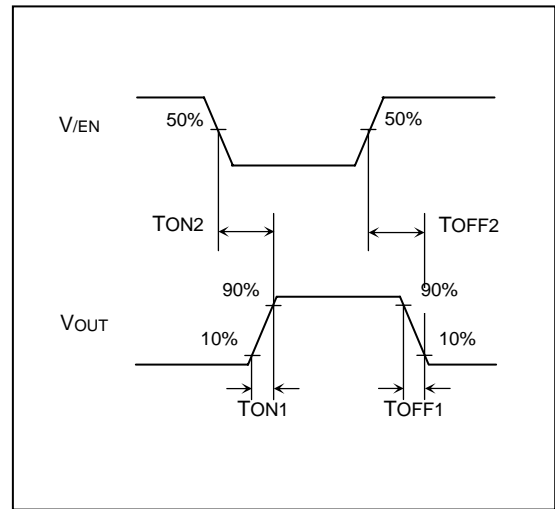


Figure 3. Output rise/fall time (BD2225G)

Typical Performance Curves

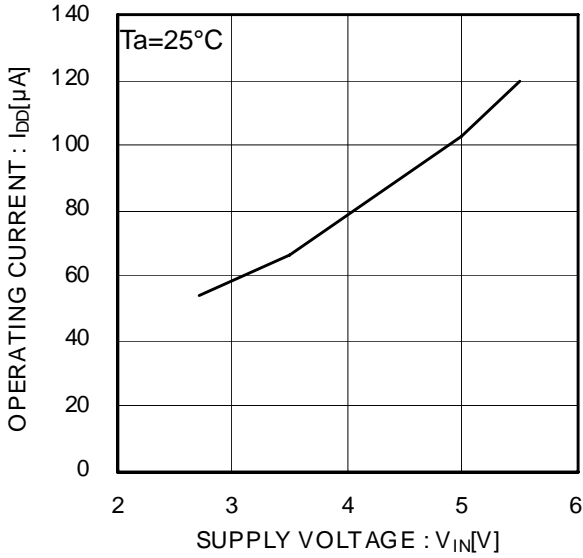


Figure 4. Operating current  
EN,/EN enable

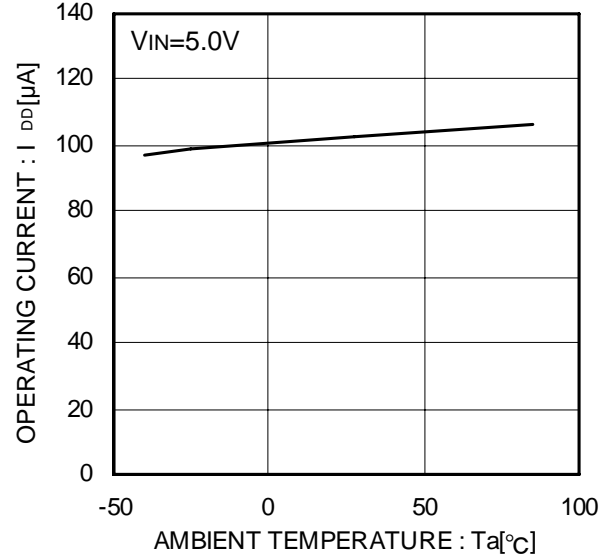


Figure 5. Operating current  
EN,/EN enable

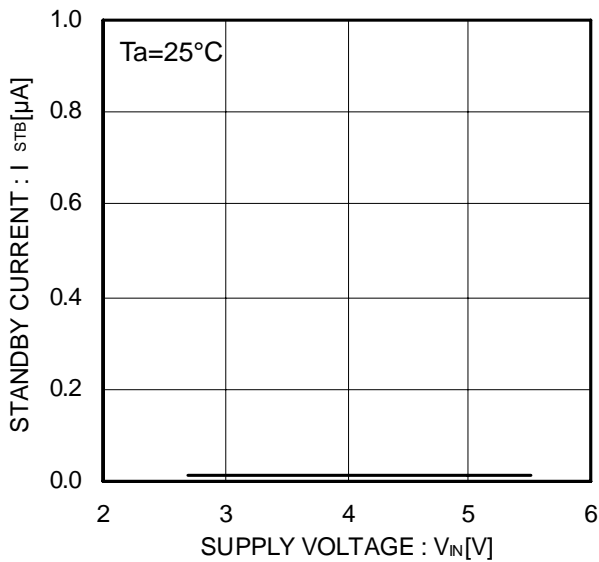


Figure 6. Standby current  
EN,/EN disable

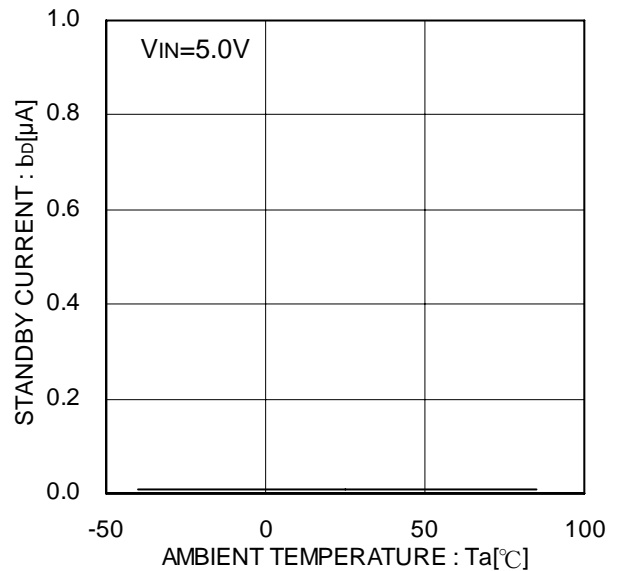


Figure 7. Standby current  
EN,/EN disable

Typical Performance Curves - continued

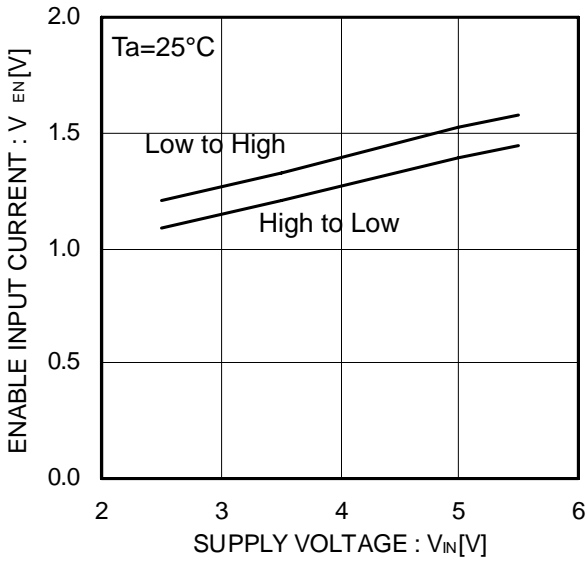


Figure 8. EN,/EN input voltage

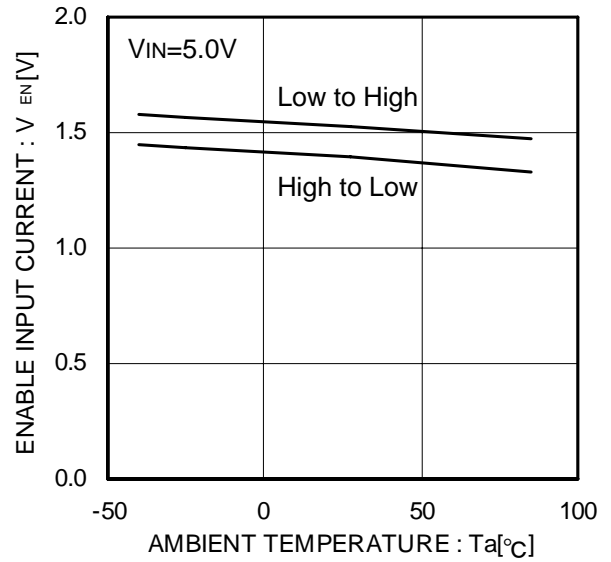


Figure 9. EN,/EN input voltage

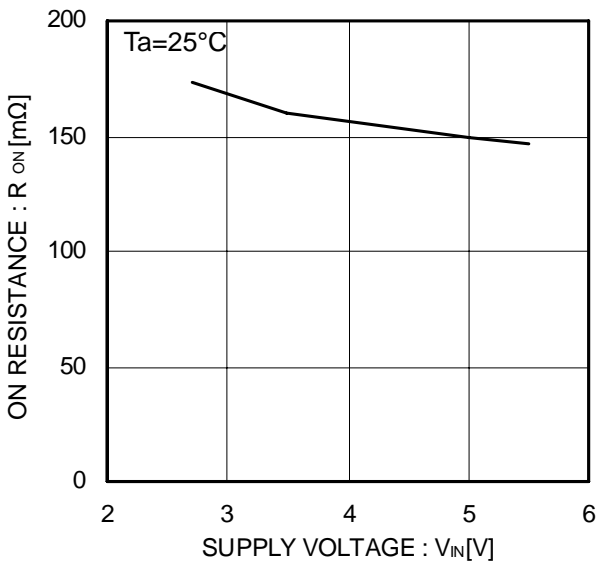


Figure 10. On-resistance

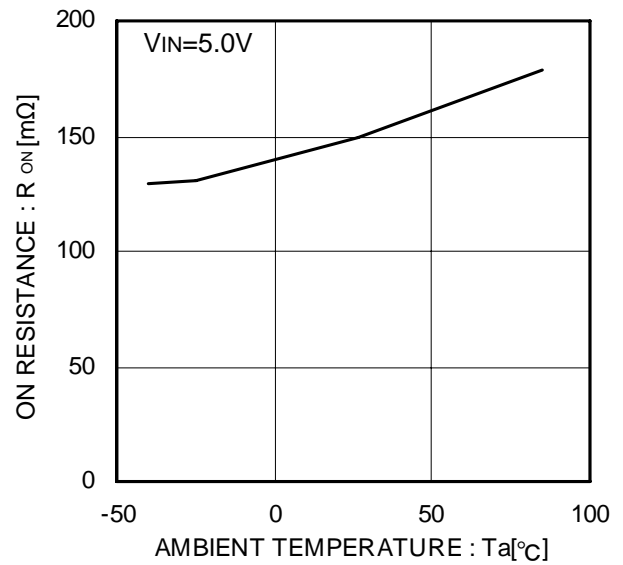


Figure 11. On-resistance

Typical Performance Curves - continued

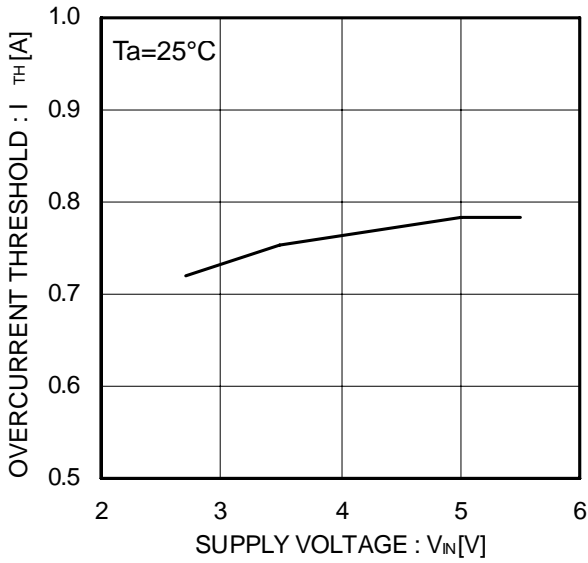


Figure 12. Over-current threshold

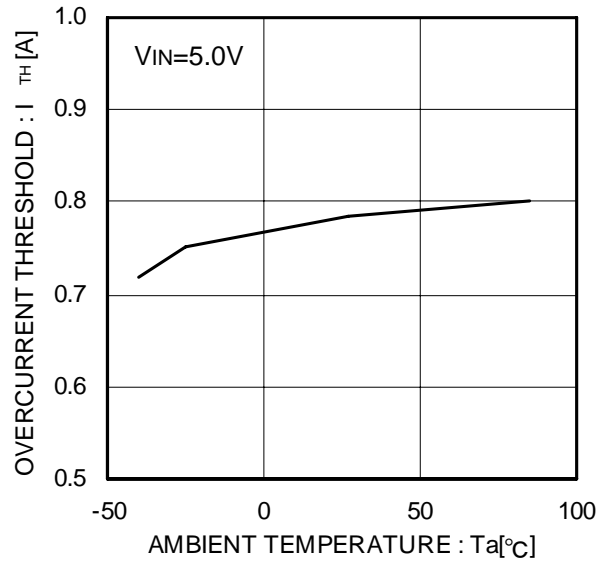


Figure 13. Over-current threshold

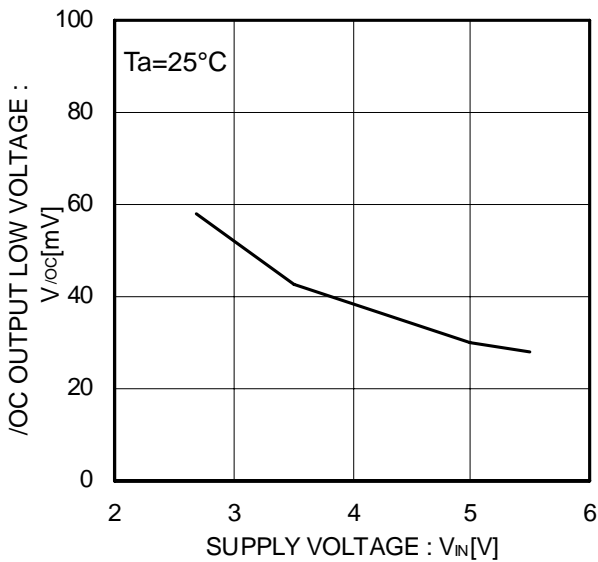


Figure 14. /OC output low voltage

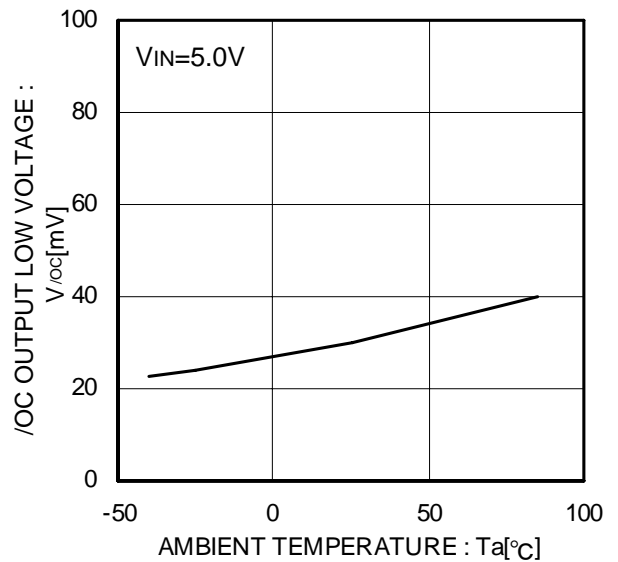


Figure 15. /OC output low voltage

Typical Performance Curves - continued

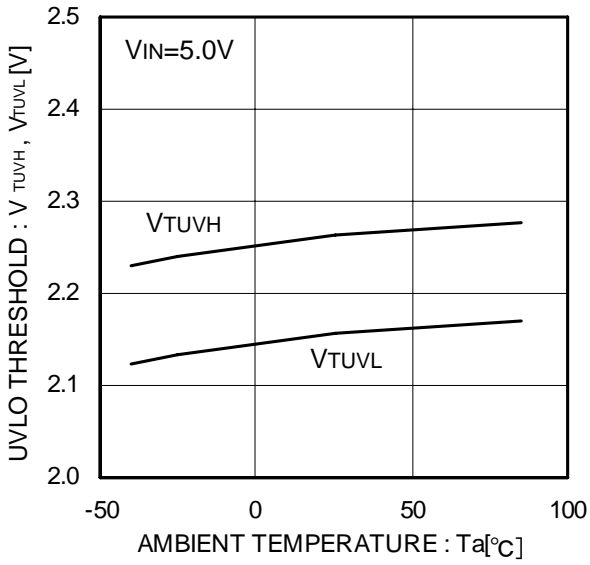


Figure 16. UVLO threshold

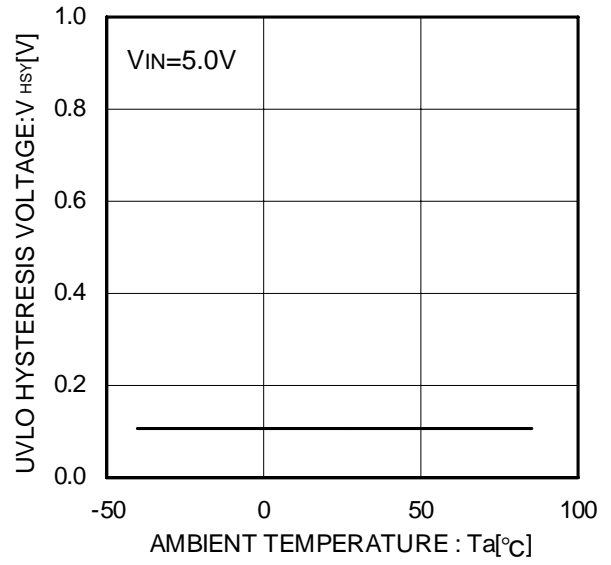


Figure 17. UVLO hysteresis voltage

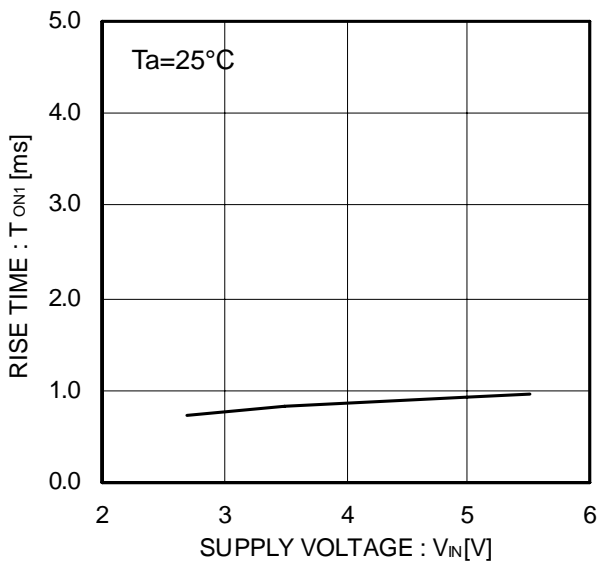


Figure 18. Output rise time

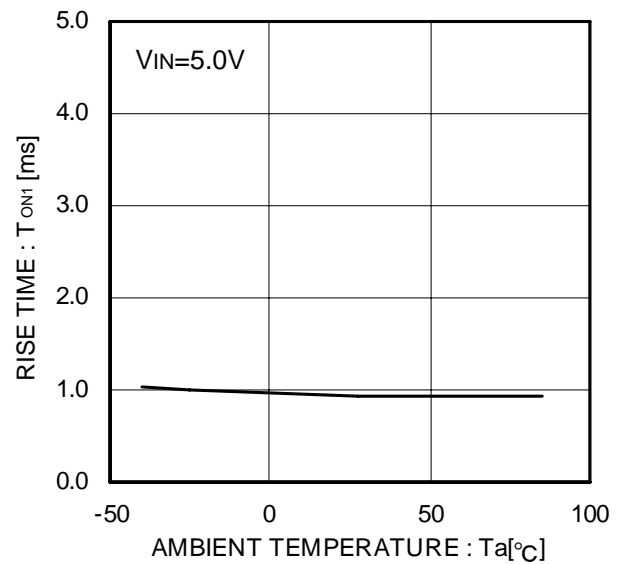


Figure 19. Output rise time



Typical Performance Curves - continued

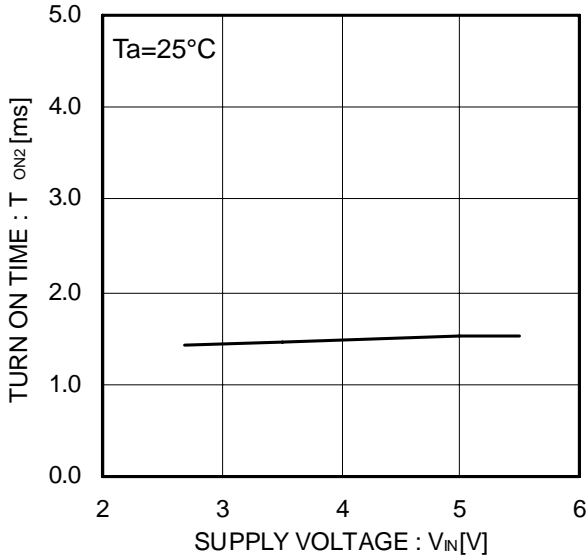


Figure 20. Output turn-on time

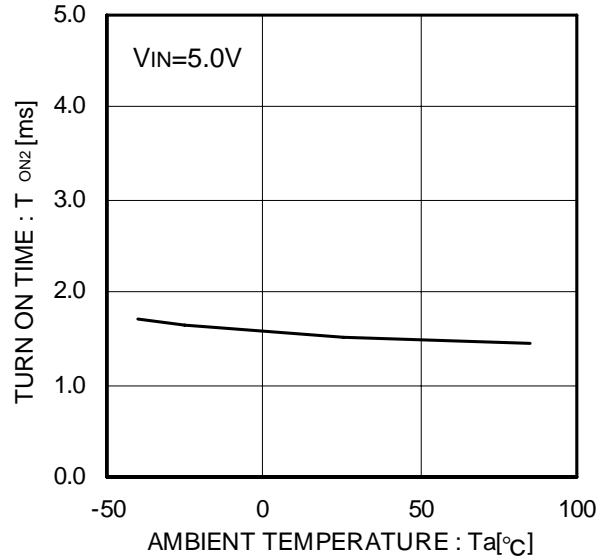


Figure 21. Output turn-on time

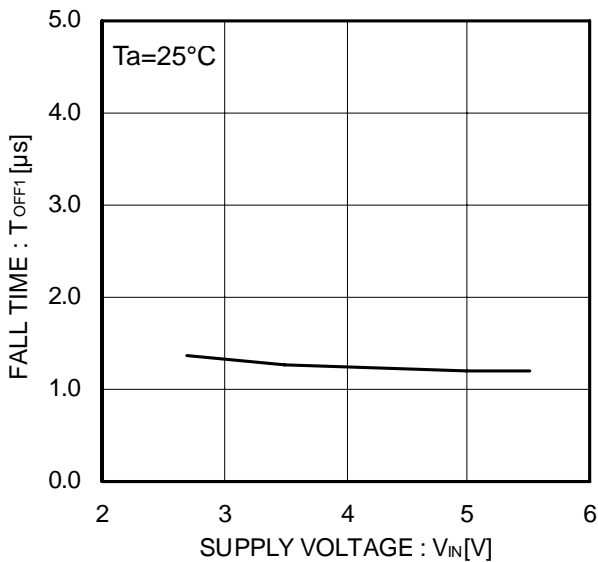


Figure 22. Output fall time

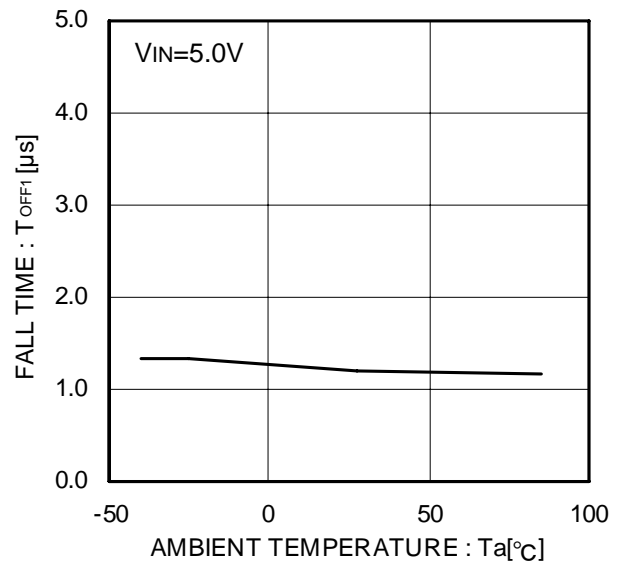


Figure 23. Output fall time

Typical Performance Curves - continued

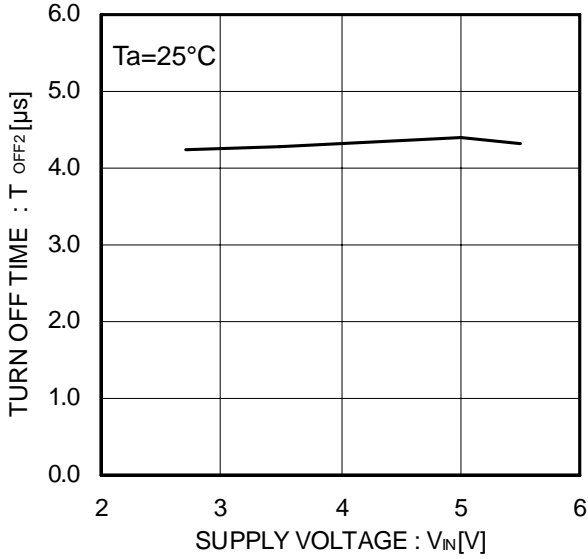


Figure 24. Output turn-off time

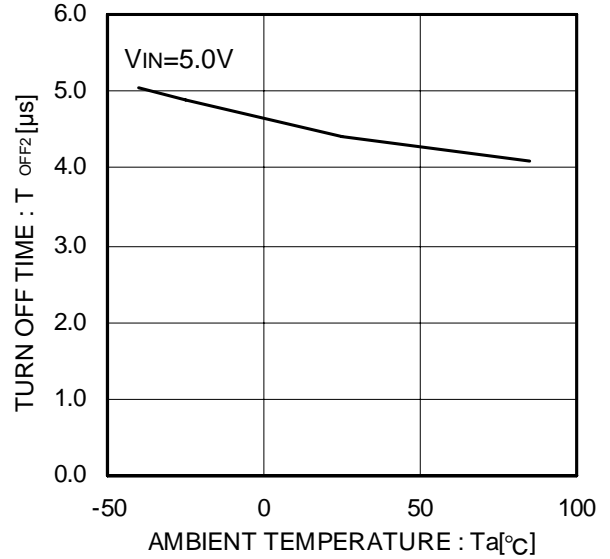


Figure 25. Output turn-off time

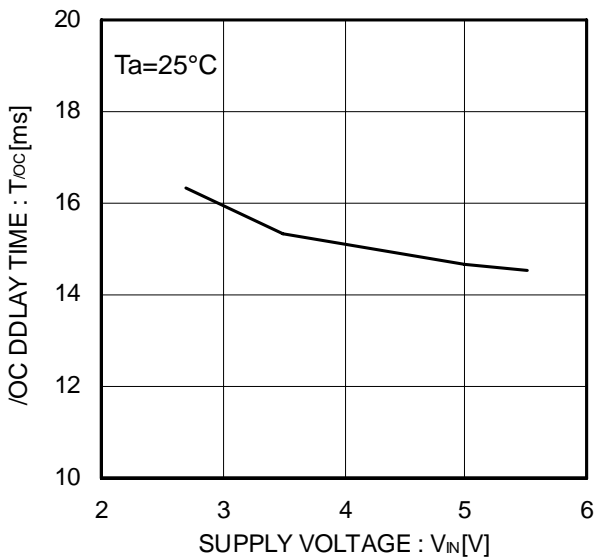


Figure 26. /OC delay time

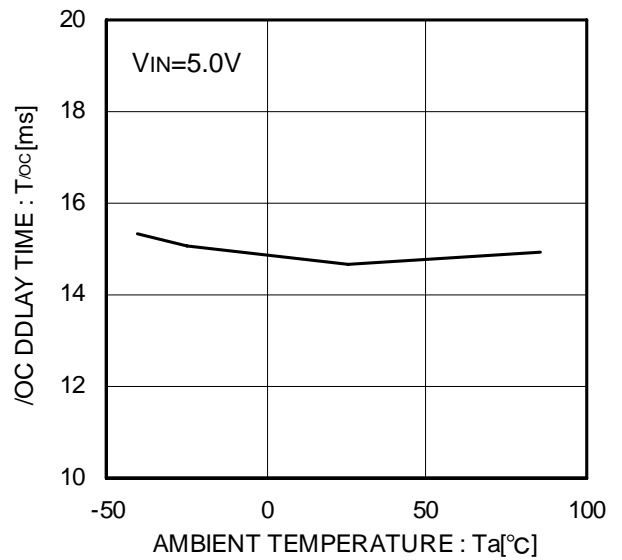


Figure 27. /OC delay time

Typical Wave Forms  
(BD2224G)

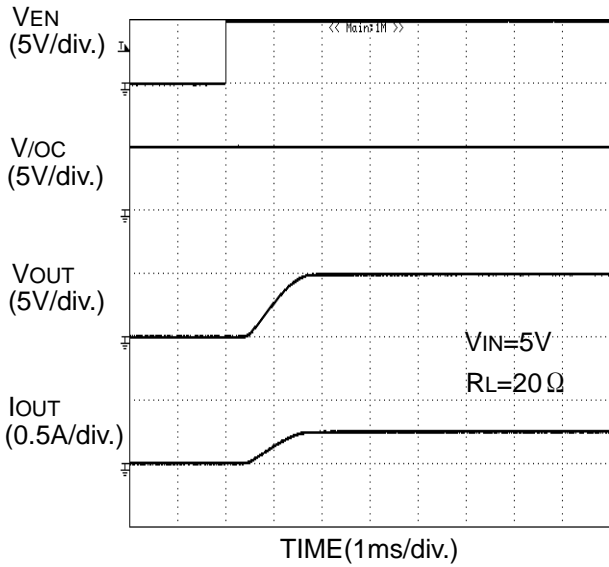


Figure 28. Output rise characteristic

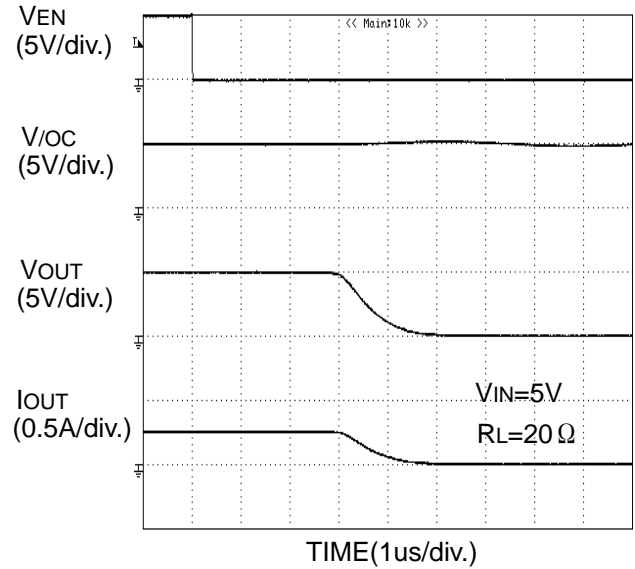


Figure 29. Output fall characteristic

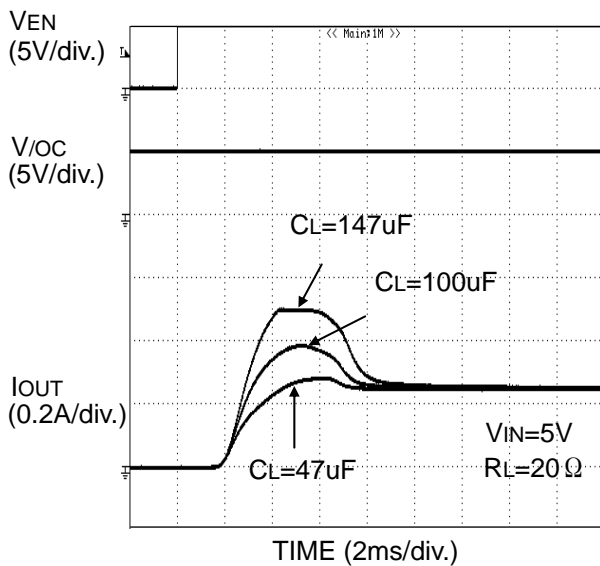


Figure 30. Inrush current response

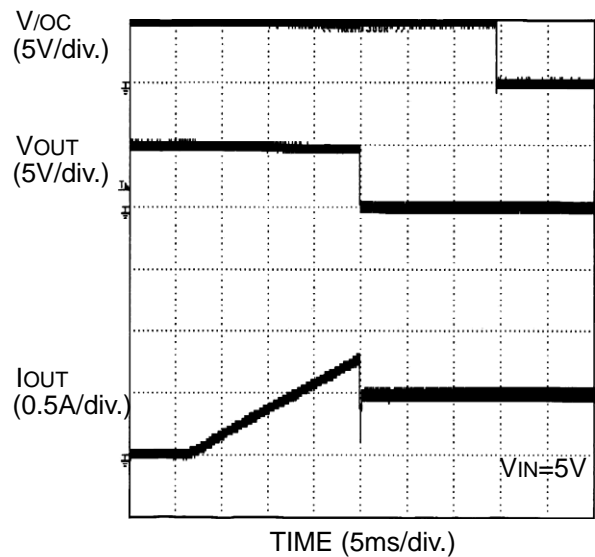


Figure 31. Over-current response  
ramped load

Typical Wave Forms - continued

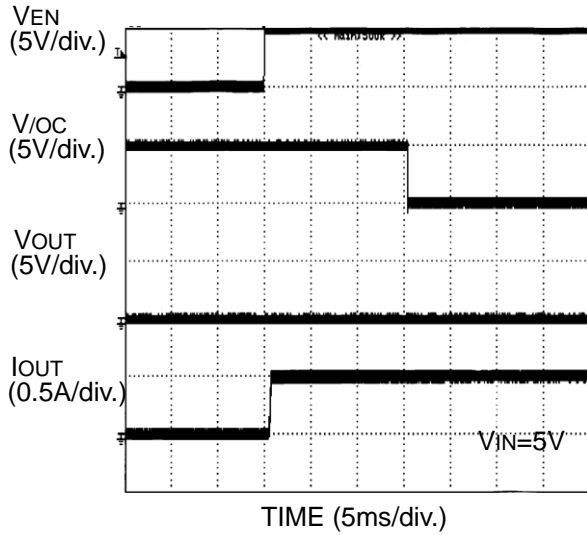


Figure 32. Over-current response enable to shortcircuit

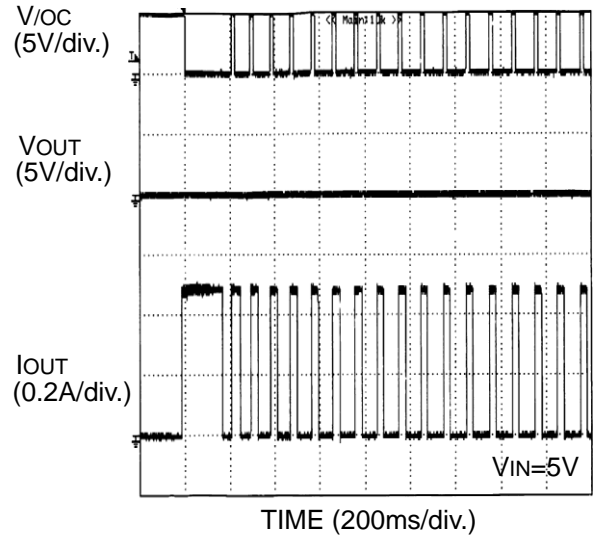


Figure 33. Over-current response enable to shortcircuit

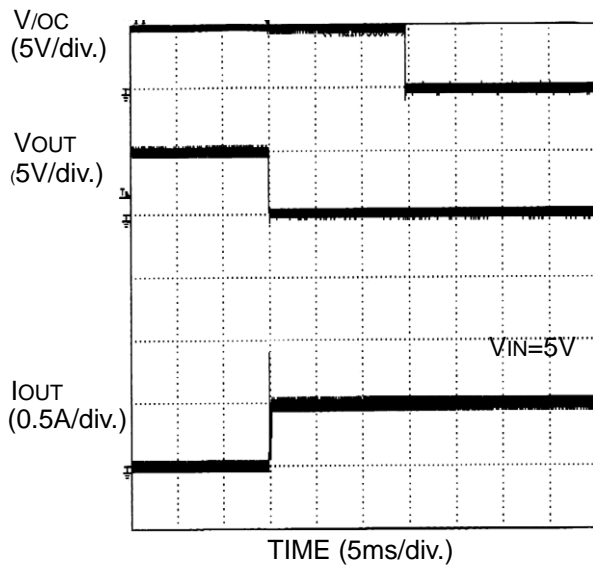


Figure 34. Over-current response enable to shortcircuit

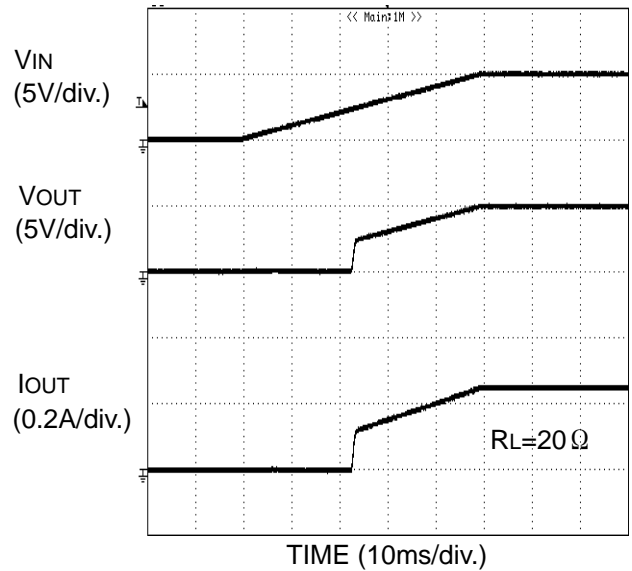


Figure 35. UVLO response increasing VIN

Typical Wave Forms - continued

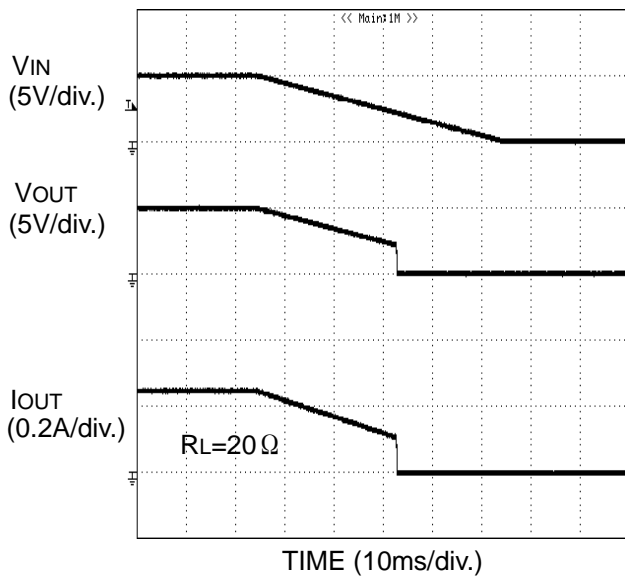
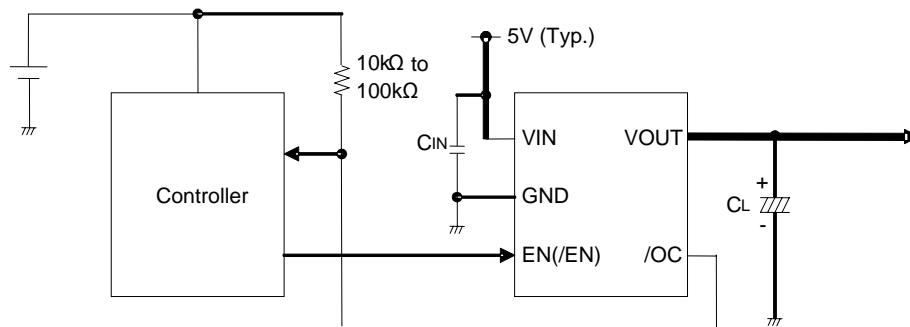


Figure 36. UVLO response decreasing VIN

Typical Application Circuit



Application Information

When excessive current flows due to output short-circuit or so, ringing occurs because of inductance between power source line to IC, and may cause bad influences on IC operations. In order to avoid this case, connect a bypass capacitor across IN terminal and GND terminal of IC. 1μF or higher is recommended.

Pull up /OC output by a 10kΩ to 100kΩ resistance.

Set up value which satisfies the application as CL.

This application circuit does not guarantee its operation.

When using the circuit with changes to the external circuit constants, make sure to leave an adequate margin for external components including AC/DC characteristics as well as dispersion of the IC.

## Functional Description

### 1. Switch Operation

VIN terminal and VOUT terminal are connected to the drain and the source of switch MOSFET respectively. And the VIN terminal is used also as power source input to internal control circuit.

When the switch is turned on from EN,/EN control input, VIN terminal and VOUT terminal are connected by a 150mΩ(Typ.) switch. In on status, the switch is bi-directional. Therefore, when the potential of VOUT terminal is higher than that of VIN terminal, current flows from VOUT terminal to VIN terminal.

### 2. Thermal Shutdown Circuit (TSD)

If over-current would continue, the temperature of the IC would increase drastically. If the junction temperature was beyond 135°C(Typ.) in the condition of over-current detection, thermal shutdown circuit operates and makes power switch turn off and outputs fault flag (/OC). Then, when the junction temperature decreases lower than 115°C(Typ.), power switch is turned on and fault flag (/OC) is disabled. Unless the increasing of the chip's temperature is removed or the output of power switch is turned off, this operation repeats.

The thermal shutdown circuit operates when the switch is on (EN,/EN signal is active).

### 3. Over-Current Detection (OCD)

The over-current detection circuit limits current ( $I_{SC}$ ) and outputs fault flag (/OC) when current flowing in each switch MOSFET exceeds a specified value. There are three types of response against over-current. The over-current detection circuit works when the switch is on (EN,/EN signal is active).

#### 3-1. When the switch is turned on while the output is in shortcircuit status

When the switch is turned on while the output is in short-circuit status, the switch goes into current limit status immediately.

#### 3-2. When the output shortcircuits while the switch is on

When the output short-circuits or high-current load is connected while the switch is on, very large current flows until the over current limit circuit reacts. When the current detection and limit circuit works, current limitation is carried out.

#### 3-3. When the output current increases gradually

When the output current increases gradually, current limitation does not work until the output current exceeds the over current detection value. When it exceeds the detection value, current limitation is carried out.

### 4. Under-Voltage Lockout (UVLO)

UVLO circuit prevents the switch from turning on until the VIN exceeds 2.3V(Typ.). If the VIN drops below 2.2V(Typ.) while the switch turns on, then UVLO shuts off the power switch. UVLO has hysteresis of a 100mV(Typ). Under-voltage lockout circuit works when the switch is on (EN,/EN signal is active).

### 5. Fault Flag (/OC) Output

Fault flag output is an N-MOS open drain output. At detection of over current and/or thermal shutdown, the output level is low.

Over-current detection has delay filter. This delay filter prevents instantaneous current detection such as inrush current at switch on, hot plug from being informed to outside.

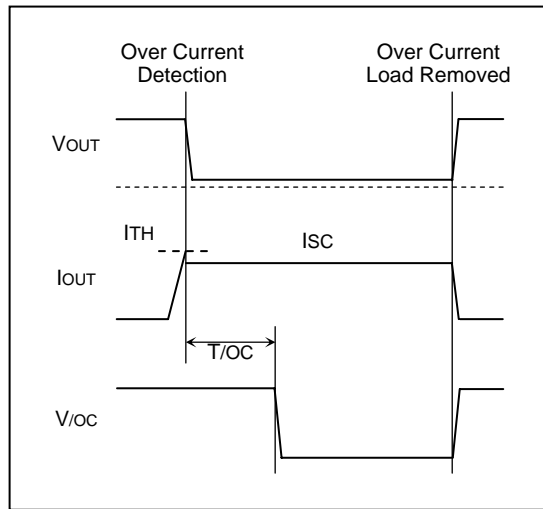


Figure 37. Over-current detection

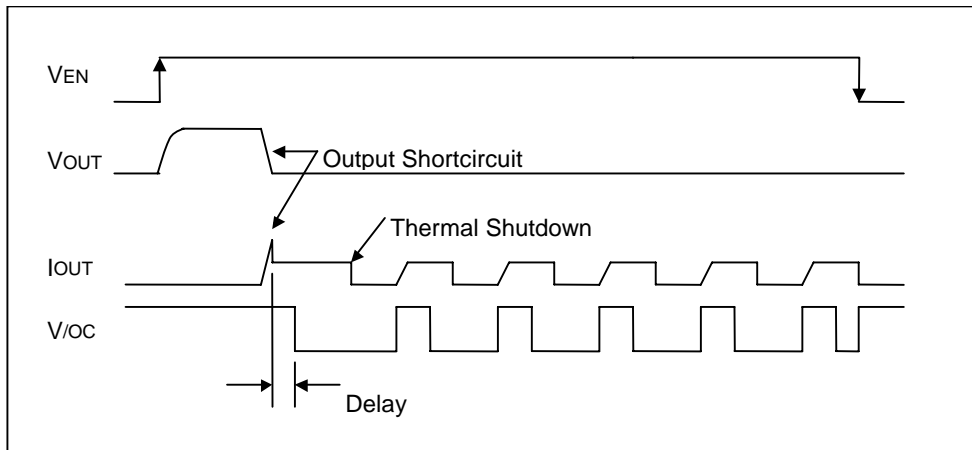


Figure 38. Over-current detection, Thermal shutdown timing (BD2224G)

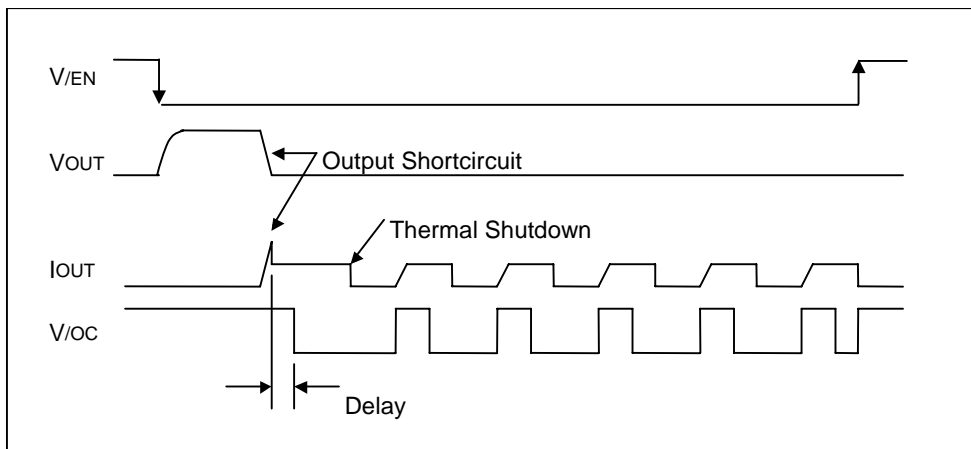
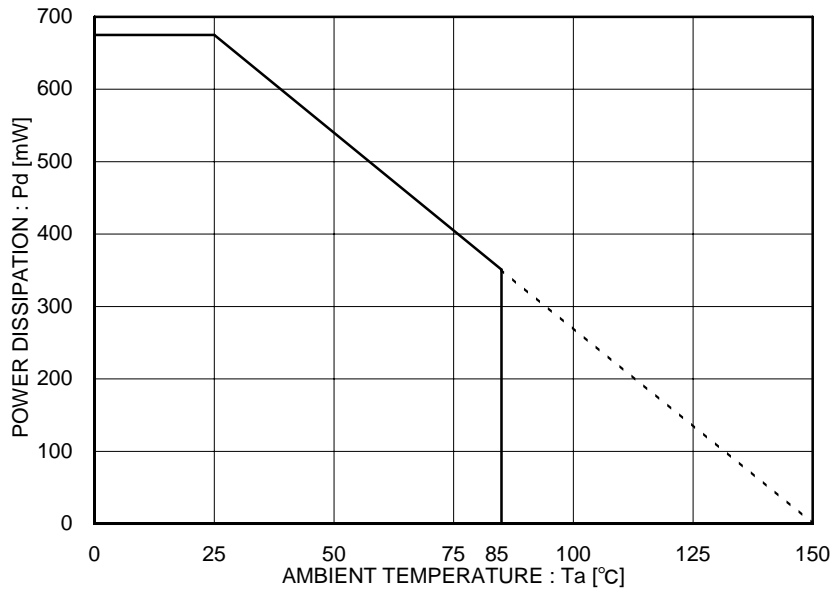


Figure 39. Over-current detection, Thermal shutdown timing (BD2225G)

**Power Dissipation**  
(SSOP5 package)



\* 70mm x 70mm x 1.6mm Glass Epoxy Board

Figure 40. Power Dissipation Curve (Pd-Ta Curve)

**I/O Equivalent Circuit**

Symbol	Pin No.	Equivalent Circuit
EN (/EN)	3	
VOUT	5	
/OC	4	



## Operational Notes

- (1) Absolute maximum ratings  
Operating the IC over the absolute maximum ratings may damage the IC. The damage can either be a short circuit between pins or an open circuit between pins. Therefore, it is important to consider circuit protection measures, such as adding a fuse, in case the IC is operated over the absolute maximum ratings.
- (2) Recommended operating conditions  
These conditions represent a range within which the expected characteristics of the IC can be approximately obtained. The electrical characteristics are guaranteed under the conditions of each parameter.
- (3) Reverse connection of power supply  
Connecting the power supply in reverse polarity can damage the IC. Take precautions against reverse polarity when connecting the power supply, such as mounting an external diode between the power supply and the IC's power supply terminals.
- (4) Power supply lines  
Design the PCB layout pattern to provide low impedance ground and supply lines. Separate the ground and supply lines of the digital and analog blocks to prevent noise in the ground and supply lines of the digital block from affecting the analog block. Furthermore, connect a capacitor to ground at all power supply pins. Consider the effect of temperature and aging on the capacitance value when using electrolytic capacitors.
- (5) Ground voltage  
The voltage of the ground pin must be the lowest voltage of all pins of the IC at all operating conditions. Ensure that no pins are at a voltage below the ground pin at any time, even during transient condition.
- (6) Short between pins and mounting errors  
Be careful when mounting the IC on printed circuit boards. The IC may be damaged if it is mounted in a wrong orientation or if pins are shorted together. Short circuit may be caused by conductive particles caught between the pins.
- (7) Operation under strong electromagnetic field  
Operating the IC in the presence of a strong electromagnetic field may cause the IC to malfunction.
- (8) Testing on application boards  
When testing the IC on an application board, connecting a capacitor directly to a low-impedance output pin may subject the IC to stress. Always discharge capacitors completely after each process or step. The IC's power supply should always be turned off completely before connecting or removing it from the test setup during the inspection process. To prevent damage from static discharge, ground the IC during assembly and use similar precautions during transport and storage.
- (9) Regarding input pins of the IC  
This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of the P layers with the N layers of other elements, creating a parasitic diode or transistor. For example (refer to figure below):

When  $GND > Pin A$  and  $GND > Pin B$ , the P-N junction operates as a parasitic diode.

When  $GND > Pin B$ , the P-N junction operates as a parasitic transistor.

Parasitic diodes inevitably occur in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Therefore, conditions that cause these diodes to operate, such as applying a voltage lower than the GND voltage to an input pin (and thus to the P substrate) should be avoided.

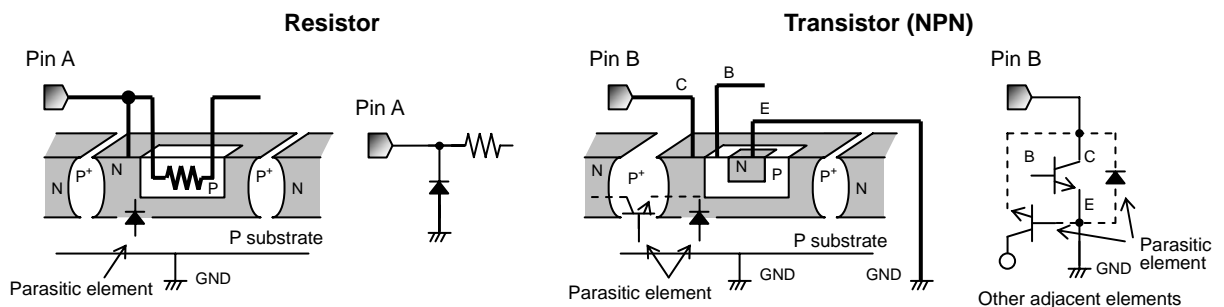


Figure 41. Example of monolithic IC structure

- (10) GND wiring pattern

When using both small-signal and large-current GND traces, the two ground traces should be routed separately but connected to a single ground at the reference point of the application board to avoid fluctuations in the small-signal ground caused by large currents. Also ensure that the GND traces of external components do not cause variations on the GND voltage. The power supply and ground lines must be as short and thick as possible to reduce line impedance.

## (11) External capacitor

When using a ceramic capacitor, determine the dielectric constant considering the change of capacitance with temperature and the decrease in nominal capacitance due to DC bias and others.

## (12) Thermal shutdown circuit (TSD)

The IC incorporates a built-in thermal shutdown circuit, which is designed to turn off the IC when the internal temperature of the IC reaches a specified value. Do not continue to operate the IC after this function is activated. Do not use the IC in conditions where this function will always be activated.

## (13) Thermal consideration

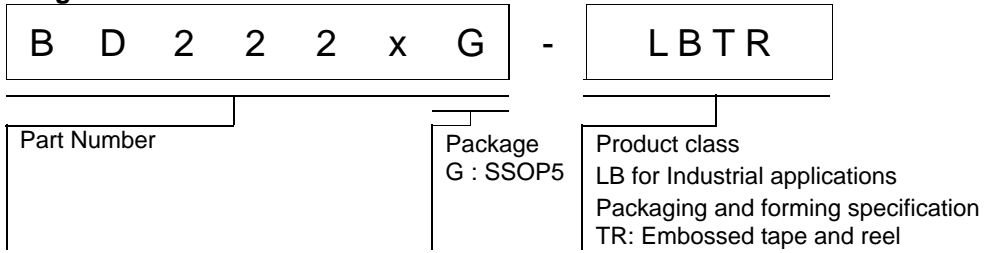
Use a thermal design that allows for a sufficient margin by taking into account the permissible power dissipation (Pd) in actual operating conditions. Consider Pc that does not exceed Pd in actual operating conditions ( $P_c \geq P_d$ ).

Package Power dissipation :  $P_d (W) = (T_{jmax} - T_a) / \theta_{ja}$

Power dissipation :  $P_c (W) = (V_{cc} - V_o) \times I_o + V_{cc} \times I_b$

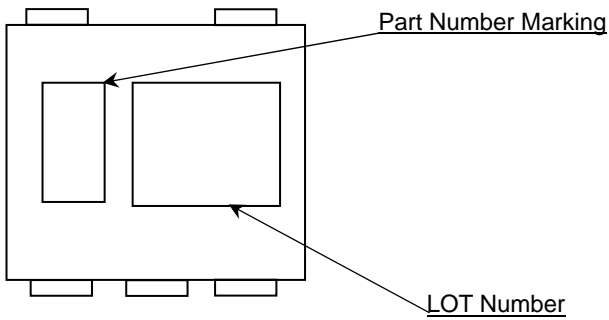
(  $T_{jmax}$  : Maximum junction temperature=150°C,  $T_a$  : Peripheral temperature[°C],  
 $\theta_{ja}$  : Thermal resistance of package-ambience[°C/W],  $P_d$  : Package Power dissipation [W],  
 $P_c$  : Power dissipation [W],  $V_{cc}$  : Input Voltage,  $V_o$  : Output Voltage,  $I_o$  : Load,  $I_b$  : Bias Current )

**Ordering Information**



**Marking Diagram**

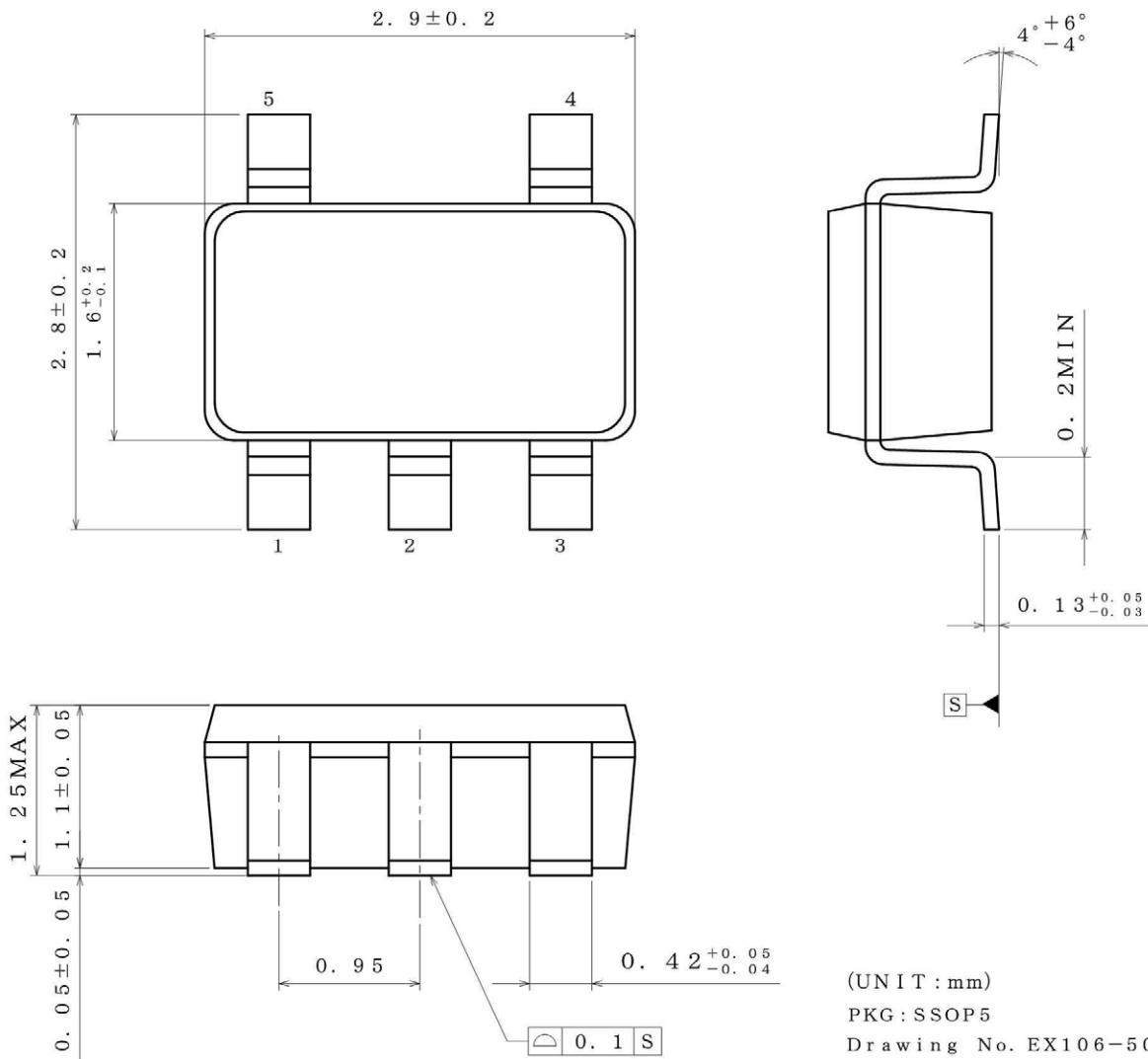
SSOP5 (TOP VIEW)



Part Number	Part Number Marking
BD2224G	DA
BD2225G	DB

Physical Dimension Tape and Reel Information

Package Name	SSOP5
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< Tape and Reel Information >

Tape	Embossed carrier tape
Quantity	3000pcs
Direction of feed	TR ( The direction is the 1pin of product is at the upper right when you hold ) reel on the left hand and you pull out the tape on the right hand



**Revision History**

Date	Revision	Changes
13.Mar.2013	001	New Release
21.Feb.2014	002	Delete sentence "and log life cycle" in General Description and Futures (page 1). Change "Industrial Applications" to "Industrial Equipment" in Applications (page 1). Applied new style ("title", "Ordering Information" and "Physical Dimension Tape and Reel Information").

# Notice

## Precaution on using ROHM Products

1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment <sup>(Note 1)</sup>, aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
  - [a] Installation of protection circuits or other protective devices to improve system safety
  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
3. Our Products are not designed under any special or extraordinary environments or conditions, as exemplified below. Accordingly, ROHM shall not be in any way responsible or liable for any damages, expenses or losses arising from the use of any ROHM's Products under any special or extraordinary environments or conditions. If you intend to use our Products under any special or extraordinary environments or conditions (as exemplified below), your independent verification and confirmation of product performance, reliability, etc, prior to use, must be necessary:
  - [a] Use of our Products in any types of liquid, including water, oils, chemicals, and organic solvents
  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
4. The Products are not subject to radiation-proof design.
5. Please verify and confirm characteristics of the final or mounted products in using the Products.
6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
8. Confirm that operation temperature is within the specified range described in the product specification.
9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

**Precautions Regarding Application Examples and External Circuits**

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
2. You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

**Precaution for Electrostatic**

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

**Precaution for Storage / Transportation**

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

**Precaution for Product Label**

QR code printed on ROHM Products label is for ROHM's internal use only.

**Precaution for Disposition**

When disposing Products please dispose them properly using an authorized industry waste company.

**Precaution for Foreign Exchange and Foreign Trade act**

Since our Products might fall under controlled goods prescribed by the applicable foreign exchange and foreign trade act, please consult with ROHM representative in case of export.

**Precaution Regarding Intellectual Property Rights**

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**General Precaution**

1. Before you use our Products, you are requested to carefully read this document and fully understand its contents. ROHM shall not be in any way responsible or liable for failure, malfunction or accident arising from the use of any ROHM's Products against warning, caution or note contained in this document.
2. All information contained in this document is current as of the issuing date and subject to change without any prior notice. Before purchasing or using ROHM's Products, please confirm the latest information with a ROHM sales representative.
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